NCTU-EE IC LAB – Spring 2024

Lab12 Check List

Self-Verify APR Result

./02_check under 09_SUMBIT to download your Lab12_iclabXXX.tar file back Create a new directory, enter the directory and decompress the tar file. Enter the decompressed directory.

- 1. Make sure your CHIP_iclabXXX.sdc is written correctly: period, waveform parameter, input delay and output delay. Waveform parameter, input delay and output delay should be half of the period.
- Invoke innonus and restore CHIP_iclabXXX.inn
 (Remember to create a new folder in case you overwrite previous design)
- 3. Explore the core size and die size, also verify if the core to IO boundary should be larger than 250.
- 4. Verifying if the IO Filler and the corner pad is added.
- 5. Verify the floorplan and powerplan constraints:
 - a. Power ring: wire group, interleaving, and at least 10 pairs, width 9.
 - b. Stripes: distance between 2 sets should be less than 200, and width 4.
 - c. Power pads: at least 1 pairs of core power pads, well connected to power ring, and at least 1 pairs of IO power pads.
- 6. Post-Route Timing analysis with non-negative slacks, 0 DRVs, core filler added.
- 7. Verifying Geometry and Connectivity after adding core filler cells.
- 8. Latency cycles in post simulation should be the same as gate level simulation.
- 9. SRAMs must be inside core region.